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TRANSISTORS, HIGH POWER, NPN

BASED ON TYPE BUX77

ESCC Detail Specification No. 5203/016

as applicable

Issue 2 3 - Draft A	February 2008
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as applicable

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DOCUMENTATION CHANGE NOTICE

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DCR No.	CHANGE DESCRIPTION
487, 324	Specification up issued to incorporate editorial and technical changes per DCRs.

447, tbd

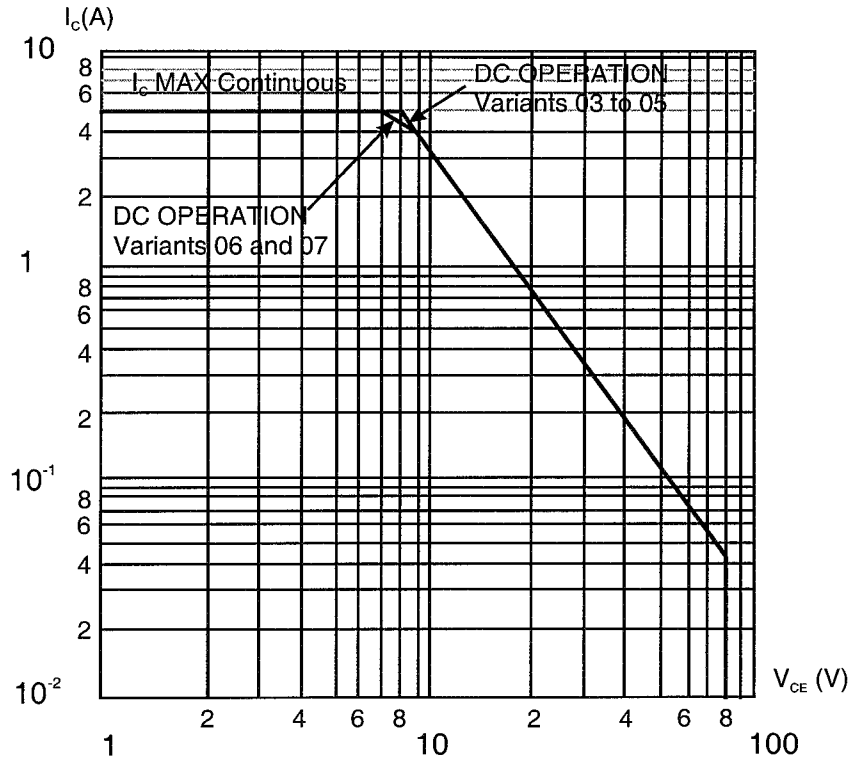
Characteristics	Symbols	Maximum Ratings	Unit	Remarks
Collector-Base Voltage	V_{CBO}	100	V	Over T_{op}
Collector-Emitter Voltage	V_{CEO}	80	V	Over T_{op} Note 4 3
Emitter-Base Voltage	V_{EBO}	6	V	Over T_{op}
Collector Current	I_C	5	A	Continuous Note 4 3
Base Current	I_B	800	mA	Continuous
Power Dissipation	P_{tot}		W	At $T_{case} \leq +25^\circ C$ Note 4 1
For TO-66		40		
For TO-257		35		
Operating Temperature Range	T_{op}	-65 to +200	$^\circ C$	Note 4 1
Storage Temperature Range	T_{stg}	-65 to +200	$^\circ C$	Note 4 1
Soldering Temperature	T_{sol}	+260	$^\circ C$	Note 4 2
Thermal Resistance, Junction-to-Case	$R_{th(j-c)}$		$^\circ C/W$	
For TO-66		4.4		
For TO-257		5		

NOTES:

- ~~1.~~ For $T_{case} > +25^\circ C$, derate linearly to 0W at $+200^\circ C$.
1. ~~4~~ For Variants with tin-lead plating or hot solder dip lead finish all testing performed at $T_{amb} > +125^\circ C$ shall be carried out in a 100% inert atmosphere.
2. ~~4~~ Duration 10 seconds maximum at a distance of not less than 1.5mm from the device body and the

3. ~~4~~ same lead shall not be resoldered until 3 minutes have elapsed.
 Safe Operation Area applies as follows:

Maximum Safe Operating Area Graph



1.6 HANDLING PRECAUTIONS

The TO-257 package contains Beryllium Oxide (BeO) and therefore it must not be ground, machined, sandblasted or subjected to any mechanical operation which will produce dust. The case must not be subjected to any chemical process (e.g. etching) which will produce fumes.

1.7 PHYSICAL DIMENSIONS AND TERMINAL IDENTIFICATION

Consolidated Notes are given following the case drawings and dimensions.

NOTES:

1. Read and record measurements shall be performed on a sample of 5 components with 0 failures allowed. Alternatively a 100% inspection may be performed.
2. Pulsed measurement: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

2.6 **PARAMETER DRIFT VALUES**

Unless otherwise specified, the measurements shall be performed at $T_{\text{amb}} = +22 \pm 3^\circ\text{C}$. The test methods and test conditions shall be as per the corresponding test defined in Room Temperature Electrical Measurements. The drift values (Δ) shall not be exceeded for each characteristic specified. The corresponding absolute limit values for each characteristic shall not be exceeded.

Characteristics	Symbols	Limits			Units
		Drift Value Δ	Absolute		
			Min	Max	
Emitter-Base Cut-off Current	I_{EBO}	± 100	-	500	nA
Forward-Current Transfer Ratio 2	$h_{\text{FE}2}$	$\pm 25\%$	50	200	-
Collector-Emitter Saturation Voltage	$V_{\text{CE(sat)}}$	± 100	-	1000	mV

2.7 **INTERMEDIATE AND END-POINT ELECTRICAL MEASUREMENTS**

Unless otherwise specified, the measurements shall be performed at $T_{\text{amb}} = +22 \pm 3^\circ\text{C}$. The test methods and test conditions shall be as per the corresponding test defined in Room Temperature Electrical Measurements. The limit values for each characteristic shall not be exceeded.

Characteristics	Symbols	Limits		Units
		Min	Max	
Collector-Emitter Cut-off Current	I_{CEO}	-	10	μA
Forward-Current Transfer Ratio 2	$h_{\text{FE}2}$	50	200	-
Collector-Emitter Saturation Voltage	$V_{\text{CE(sat)}}$	-	1	V

2.8 **POWER BURN-IN CONDITIONS**

Characteristics	Symbols	Conditions	Units
Case Temperature	T_{case}	+100 (+0 -5) (1)	$^\circ\text{C}$
Power Dissipation	P_{tot}	As per Maximum Ratings P_{tot} derated at the specified T_{case}	W
Collector-Emitter Voltage	V_{CE}	10	V

NOTES:

1. No heat sink nor forced air directly on the device shall be permitted.

Derate

using the specified $R_{\text{th}(j-c)}$.

APPENDIX 'A'AGREED DEVIATIONS FOR STMICROELECTRONICS (F)

ITEMS AFFECTED	DESCRIPTION OF DEVIATIONS
Deviations from Room Temperature Electrical Measurements	All AC characteristics (Room Temperature Electrical Measurement Note 2) may be considered guaranteed but not tested if successful pilot lot testing has been performed on the wafer lot which includes AC characteristic measurements per the Detail Specification. A summary of the pilot lot testing shall be provided if required by the Purchase Order.
Deviations from High and Low Temperatures Electrical Measurements	All characteristics specified may be considered guaranteed but not tested if successful pilot lot testing has been performed on the wafer lot which includes characteristic measurements at high and low temperatures per the Detail Specification. A summary of the pilot lot testing shall be provided if required by the Purchase Order.
Deviations from Screening Tests - Chart F3	Solderability is not applicable unless specifically stipulated in the Purchase Order.

(Approved DCE 447 refers)